

ABSTRACT

A silicon standoff acts as a shim during reflow between a module and a printed circuit board. The silicon standoff is attached to a flexible circuit. A ball grid array interposes the connection pads of the module and the printed circuit board. The height of the standoff is determined based on the amount of ball collapse that is desired. During reflow, the silicon standoff will not collapse, therefore the ball grid array can only collapse as far as the standoff allows before contacting the printed circuit board.